Please replace the paragraph starting on page 13, line 25 in its entirety with the following paragraph:

In the illustrated embodiment, the flexure member 30 is made of a sheet of a corrosion resistant steel (for example, SUS304TA) of approximately 25 μm thick. The flexure member 30 is smaller in width than the load beam 31. To provide the flexure member 30 with a corrosion resistant steel sheet as described is advantageous as compared with a structure wherein the flexure member is totally made of plastics material. Where the flexure member is totally made of plastics material, flatness of the slider attachment surface may very often not be satisfactory, and the slider attachment surface may be accurately parallel with the movable arm attachment surface. By providing the flexure member 30 with a corrosion resistant steel as described, the aforementioned problems can be avoided.

C4

In the Claims:

Please amend claims 13-18 and 25-29, inclusive, as follows:

C5

13. (Amended) A method of fabricating a magnetic disc device comprising a magnetic head device including a slider having a magnetic head element and a suspension structure having one end supporting the slider, a head IC chip which is a separately-formed component from the slider, a rotatable magnetic disc which is rotated at least when the head IC chip is in operation, and an electrically conductive connecting device for establishing an electrical connection between the magnetic head element and the head IC chip, the method including the steps of:

mounting the head IC chip on the connecting device at a mounting position so as to face the magnetic disc; and

selecting the mounting position of the head IC chip to be located on the connecting device where the head IC chip is always exposed to a flow of air produced by rotations of the magnetic disc so that the head IC chip is continuously cooled by the flow of air at least when the head IC chip is in operation.

14. (Amended) The method of claim 13 wherein the step of mounting the head IC chip on the suspension structure includes mounting the head IC chip which is a bare chip.

15. (Amended) The method of claim 13 wherein the step of mounting the head IC chip on the suspension structure includes mounting the head IC chip on the suspension structure by flip-chip-bonding.

16. (Amended) The method of claim 13 wherein the step of mounting the head IC chip on the suspension structure includes mounting the head IC chip which has a mass smaller than 1.0 mg.

17. (Amended) The method of claim 13 wherein the step of selecting the mounting position of a head IC chip includes selecting the mounting position of the head IC chip so that the head IC chip is located inside an outer periphery of the magnetic disc at least when the head IC chip is in operation.

18. (Amended) A method of increasing cooling of a head IC chip in a magnetic disc device comprising a magnetic head device including a slider having magnetic head element and a suspension structure having one end supporting the slider, a head IC chip which is a separately-formed component from the slider, a rotatable magnetic disc which is rotated at least when the head IC chip is in operation, and an electrically conductive connecting device for establishing an electrical connection between the magnetic head element and the head IC chip, the method including the steps of:

mounting the head IC chip on the connecting device at a mounting position so as to face the magnetic disc; and

selecting the mounting position of the head IC chip to be located on the connecting device where the head IC chip is always exposed to a flow of air produced by rotations of the magnetic disc so that the head IC chip is continuously cooled by the flow of air at least when the head IC chip is in operation.

25. (Amended) The method of claim 24 wherein the step of mounting a head IC chip on the suspension structure includes mounting the head IC chip which is a bare chip.

26. (Amended) The method of claim 24 wherein the step of mounting a head IC chip on the suspension structure includes mounting the head IC chip on the suspension structure by flip-chip-bonding.

27. (Amended) The method of claim 24 wherein the step of mounting the head IC chip on the suspension structure includes mounting the head IC chip which has a mass smaller than 1.0 mg.

C4 cont'd

28. (Amended) The method of claim 24 wherein the step of selecting the mounting position of the head IC chip includes selecting the mounting position of the head IC chip so that the head IC chip is located inside an outer periphery of the magnetic disc at least when the head IC chip is in operation.

29. (Amended) A method of increasing cooling of a head IC chip in a magnetic disc device comprising a magnetic head device including a slider having a magnetic head element and a suspension structure having one end supporting the slider, a head IC chip which is a separately-formed component from the slider, a rotatable magnetic disc which is rotated at least when the head IC chip is in operation, and an electrically conductive connecting device for establishing an electrical connection between the magnetic head element and the head IC chip, the method including the steps of:

mounting the head IC chip on the connecting device at a position so as to face the magnetic disc;

selecting the mounting position of the head IC chip to be located on the connecting device where the head IC chip is always exposed to a flow of air produced by rotations of the magnetic disc so that the head IC chip is continuously cooled by the flow of air at least when the head IC chip is in operation; and

arranging for the head IC chip to be located with respect to the magnetic disc with a distance between opposing surfaces of the head IC chip and the magnetic disc smaller than 1000 μm.